MICROCHIP

Semiconductor Device Type:	C2X	SOIC 8 3.90mm Matte Tin			
Basic Substance	**CAS Number**	**"Contained In" Sub-Component**	**% Total Weight**	**mg/part**	**ppm**
Silicon	7440-21-3	Die	9.60	10.27	96024
Copper	7440-50-8	Lead Frame	26.28	28.11	262751
Iron	7439-89-6	Lead Frame	0.63	0.68	6341
Phosphorus	7723-14-0	Lead Frame	0.02	0.02	216
Zinc	7440-66-6	Lead Frame	0.04	0.04	351
Lead	7439-92-1	Lead Frame	0.00	0.00	27
Silver	7440-22-4	Lead Frame Plating	0.01	0.01	135
Amorphous Silica	60676-86-0	Mold Compound	54.56	58.36	545556
Phenol Resin	Trade Secret	Mold Compound	2.49	2.66	24883
Epoxy Resin#2	Trade Secret	Mold Compound	2.18	2.33	21772
Epoxy Resin#1	Trade Secret	Mold Compound	1.87	2.00	18662
Crystal silica	Trade Secret	Mold Compound	0.93	1.00	9331
Carbon black	1333-86-4	Mold Compound	0.19	0.20	1866
Gold	7440-57-5	Bonding Wire	1.08	1.16	10805
Impurities	Trade Secret	Bonding Wire	0.00	0.00	1
Silver	7440-22-4	Die Attach Epoxy	0.10	0.11	1014
2,2′-[[2-(2-Oxiranylmethoxy)-1,3-phenylene]bis(methylene)]bis[oxirane]	13561-08-5	Die Attach Epoxy	0.01	0.01	74
Fatty acids, C18-unsatd., dimers, polymers with epichlorohydrin	68475-94-5	Die Attach Epoxy	0.01	0.01	74
Formaldehyde, polymer with 2-(chloromethyl)oxirane and phenol	9003-36-5	Die Attach Epoxy	0.01	0.01	74
Tin	7440-31-5	Lead Finish Plating	0.00	0.00	41
		TOTALS:	**100.00**	**106.98**	**1,000,000**

106.98 mg Total Mass

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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Package Homogeneous Materials

10.27	**(mg) Total**	**Die**	**% of Total Weight**	**9.60**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
28.85	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**26.97**
	Copper	7440-50-8	97.43	
	Iron	7439-89-6	2.35	
	Phosphorus	7723-14-0	0.08	
	Zinc	7440-66-6	0.13	
	Lead	7439-92-1	0.01	
		Total	**100.00**	
0.01	**(mg) Total**	**Lead Frame Plating**	**% of Total Weight**	**0.01**
	Silver	7440-22-4	100.00	
		Total	**100.00**	
66.55	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**62.21**
	Amorphous Silica	60676-86-0	87.70	
	Phenol Resin	Trade Secret	4.00	
	Epoxy Resin#2	Trade Secret	3.50	
	Epoxy Resin#1	Trade Secret	3.00	
	Crystal silica	Trade Secret	1.50	
	Carbon black	1333-86-4	0.30	
		Total	**100.00**	
1.16	**(mg) Total**	**Bonding Wire**	**% of Total Weight**	**1.08**
	Gold	7440-57-5	99.99	
	Impurities	Trade Secret	0.01	
		Total	**100.00**	
0.13	**(mg) Total**	**Die Attach Epoxy**	**% of Total Weight**	**0.12**
	Silver	7440-22-4	82.00	
	2,2′-[[2-(2-Oxiranylmethoxy)-1,3-phenylene]bis(methyler	13561-08-5	6.00	
	Fatty acids, C18-unsatd., dimers, polymers with epic	68475-94-5	6.00	
	Formaldehyde, polymer with 2-(chloromethyl)oxirane	9003-36-5	6.00	
		Total	**100.00**	
0.00	**(mg) Total**	**Lead Finish Plating**	**% of Total Weight**	**0.00**
	Tin	7440-31-5	100.00	
106.98		**Total**	**100.00**	100.00